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**TLE2426-EP**  
**RAIL SPLITTER**  
**PRECISION VIRTUAL GROUND**

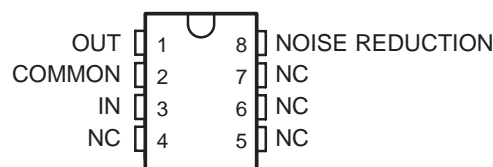
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- **Controlled Baseline**
  - One Assembly/Test Site, One Fabrication Site
- **Extended Temperature Performance of –55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree†**
- **One-Half  $V_I$  Virtual Ground for Analog Systems**
- **Micropower Operation . . . 170  $\mu$ A Typ,  $V_I = 5$  V**
- **Wide  $V_I$  Range . . . 4 V to 40 V**
- **High Output-Current Capability**
  - Source . . . 20 mA Typ
  - Sink . . . 20 mA Typ

- **Excellent Output Regulation**
  - –102  $\mu$ V Typ at  $I_O = 0$  mA to –10 mA
  - 49  $\mu$ V Typ at  $I_O = 0$  mA to 10 mA
- **Low-Impedance Output . . . 0.0075  $\Omega$  Typ**
- **Noise Reduction Pin**

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

**D PACKAGE**  
**(TOP VIEW)**



NC – No internal connection

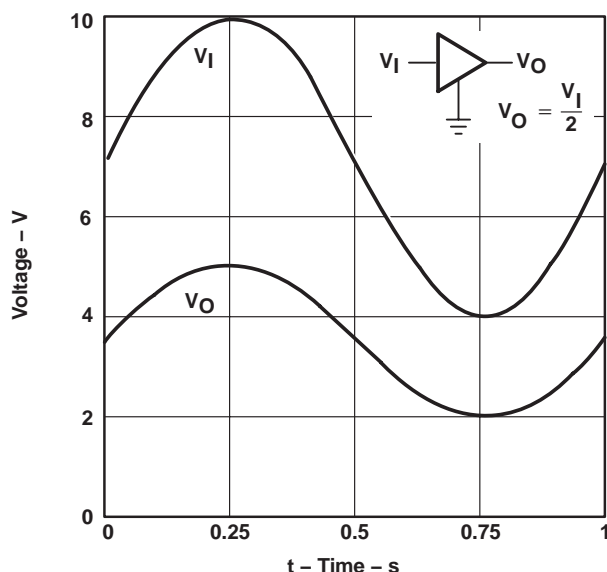
**description/ordering information**

In signal-conditioning applications utilizing a single power source, a reference voltage equal to one-half the supply voltage is required for termination of all analog signal grounds. TI presents a precision virtual ground whose output voltage is always equal to one-half the input voltage—the TLE2426 rail splitter.

The unique combination of a high-performance, micropower operational amplifier and a precision-trimmed divider on a single silicon chip results in a precise  $V_O/V_I$  ratio of 0.5 while sinking and sourcing current. The TLE2426 provides a low-impedance output with 20 mA of sink and source capability, while drawing less than 280  $\mu$ A of supply current over the full input range of 4 V to 40 V. A designer need not pay the price in terms of board space for a conventional signal ground consisting of resistors, capacitors, operational amplifiers, and voltage references. For increased performance, the 8-pin package provides a noise-reduction pin. With the addition of an external capacitor ( $C_{NR}$ ), peak-to-peak noise is reduced, while line ripple rejection is improved.

Initial output tolerance for a single 5-V or 12-V system is better than 1% over the full 40-V input range. Ripple rejection exceeds 12 bits of accuracy. Whether the application is for a data-acquisition front end, analog signal termination, or simply a precision voltage reference, the TLE2426 eliminates a major source of system error.

**INPUT/OUTPUT TRANSFER CHARACTERISTICS**



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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**ORDERING INFORMATION**

T <sub>A</sub>	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-55°C to 125°C	SOIC (D)	Tape and reel	TLE2426MDREP	2426EP

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

**absolute maximum ratings over operating free-air temperature (unless otherwise noted)†**

Continuous input voltage, V <sub>I</sub>	40 V
Continuous filter trap voltage	40 V
Output current, I <sub>O</sub>	±80 mA
Duration of short-circuit current at (or below) 25°C (see Note 1)	Unlimited
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T <sub>A</sub>	-55°C to 125°C
Operating junction temperature, T <sub>J</sub> (see Note 2)	150°C
Storage temperature range, T <sub>stg</sub> (see Note 2)	150°C
Lead temperature 1,6 mm (1/16 in) from case for 10 s	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The output may be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded.  
 2. Long-term high-temperature storage and/or usage at the absolute maximum ratings may result in a reduction of overall device life. See [http://www.ti.com/ep\\_quality](http://www.ti.com/ep_quality) for additional information on enhanced plastic packaging.

**DISSIPATION RATING TABLE**

PACKAGE	T <sub>A</sub> ≤ 25°C	DERATING FACTOR	T <sub>A</sub> = 70°C	T <sub>A</sub> = 85°C	T <sub>A</sub> = 125°C
	POWER RATING	ABOVE T <sub>A</sub> = 25°C	POWER RATING	POWER RATING	POWER RATING
D	1102 mW	10.3 mW/°C	638.5 mW	484 mW	72.1 mW

**recommended operating conditions**

	MIN	MAX	UNIT
Input voltage, V <sub>I</sub>	4	40	V
Operating free-air temperature, T <sub>A</sub>	-55	125	°C

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**electrical characteristics at specified free-air temperature,  $V_I = 5\text{ V}$ ,  $I_O = 0$  (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		$T_A$ †	MIN	TYP	MAX	UNIT
Output voltage	$V_I = 4\text{ V}$		25°C	1.98	2	2.02	V
	$V_I = 5\text{ V}$			2.48	2.5	2.52	
	$V_I = 40\text{ V}$			19.8	20	20.2	
	$V_I = 5\text{ V}$		Full range	2.465		2.535	
Temperature coefficient of output voltage			Full range	25			ppm/°C
Supply current	No load	$V_I = 5\text{ V}$	25°C	170	300		μA
		$V_I = 4\text{ to }40\text{ V}$	25°C	350			
			Full range	400			
Output voltage regulation (sourcing current)‡	$I_O = 0\text{ to }-10\text{ mA}$		25°C	-0.102	±0.7		mV
			Full range	±10			
Output voltage regulation (sinking current)‡	$I_O = 0\text{ to }-20\text{ mA}$		25°C	-0.121	±1.4		mV
	$I_O = 0\text{ to }10\text{ mA}$		25°C	0.049	±0.5		
	$I_O = 0\text{ to }8\text{ mA}$		Full range	±10			
	$I_O = 0\text{ to }20\text{ mA}$		25°C	0.175	±1.4		
Output impedance‡			25°C	7.5	22.5		mΩ
Noise-reduction impedance			25°C	110			kΩ
Short-circuit current	Sinking current, $V_O = 5\text{ V}$		25°C	26			mA
	Sourcing current, $V_O = 0$			-47			
Output noise voltage, rms	$f = 10\text{ Hz to }10\text{ kHz}$	$C_{NR} = 0$	25°C	120			μV
		$C_{NR} = 1\text{ μF}$		30			
Output voltage current step response	$V_O\text{ to }0.1\%, I_O = \pm 10\text{ mA}$	$C_L = 0$	25°C	290			μs
		$C_L = 100\text{ pF}$		275			
	$V_O\text{ to }0.01\%, I_O = \pm 10\text{ mA}$	$C_L = 0$	25°C	400			
		$C_L = 100\text{ pF}$		390			
Step response	$V_I = 0\text{ to }5\text{ V}, V_O\text{ to }0.1\%$		25°C	20			μs
	$V_I = 0\text{ to }5\text{ V}, V_O\text{ to }0.01\%$			120			

† Full range is -55°C to 125°C.

‡ The listed values are not production tested.

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**electrical characteristics at specified free-air temperature,  $V_I = 12\text{ V}$ ,  $I_O = 0$  (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		$T_A$ †	MIN	TYP	MAX	UNIT
Output voltage	$V_I = 4\text{ V}$		25°C	1.98	2	2.02	V
	$V_I = 12\text{ V}$			5.95	6	6.05	
	$V_I = 40\text{ V}$			19.8	20	20.2	
	$V_I = 12\text{ V}$		Full range	5.925		6.075	
Temperature coefficient of output voltage			Full range	35		ppm/°C	
Supply current	No load	$V_I = 12\text{ V}$	25°C	195	300	µA	
		$V_I = 4\text{ to }40\text{ V}$	25°C	350			
			Full range	400			
Output voltage regulation (sourcing current)‡	$I_O = 0\text{ to }-10\text{ mA}$		25°C	-1.48	±10	mV	
			Full range	±10			
	$I_O = 0\text{ to }-20\text{ mA}$		25°C	-3.9	±10		
Output voltage regulation (sinking current)‡	$I_O = 0\text{ to }10\text{ mA}$		25°C	2.27	±10	mV	
	$I_O = 0\text{ to }8\text{ mA}$		Full range	±10			
	$I_O = 0\text{ to }20\text{ mA}$		25°C	4.3	±10		
Output impedance‡			25°C	7.5	22.5	mΩ	
Noise-reduction impedance			25°C	110		kΩ	
Short-circuit current	Sinking current, $V_O = 12\text{ V}$		25°C	31		mA	
	Sourcing current, $V_O = 0$			-70			
Output noise voltage, rms	$f = 10\text{ Hz to }10\text{ kHz}$	$C_{NR} = 0$	25°C	120		µV	
		$C_{NR} = 1\text{ µF}$		30			
Output voltage current step response	$V_O\text{ to }0.1\%, I_O = \pm 10\text{ mA}$		25°C	$C_L = 0$		µs	
				$C_L = 100\text{ pF}$			
	$V_O\text{ to }0.01\%, I_O = \pm 10\text{ mA}$		25°C	$C_L = 0$			
				$C_L = 100\text{ pF}$			
Step response	$V_I = 0\text{ to }12\text{ V}, V_O\text{ to }0.1\%$		25°C	12		µs	
	$V_I = 0\text{ to }12\text{ V}, V_O\text{ to }0.01\%$			120			

† Full range is -55°C to 125°C.

‡ The listed values are not production tested.

**TYPICAL CHARACTERISTICS**

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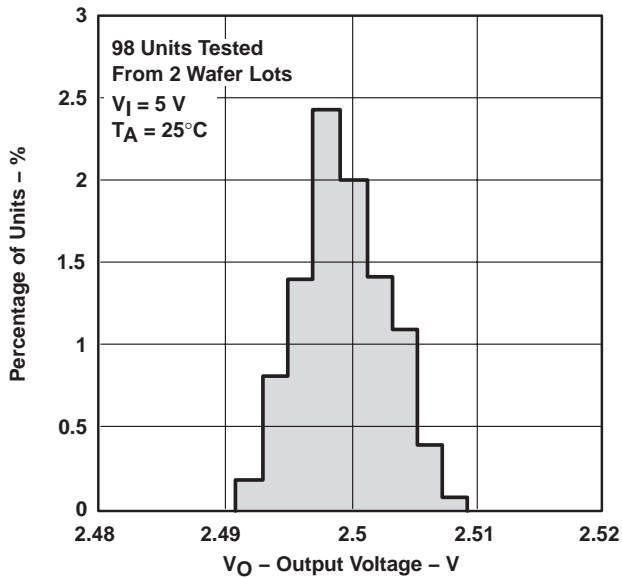
		<b>FIGURE</b>
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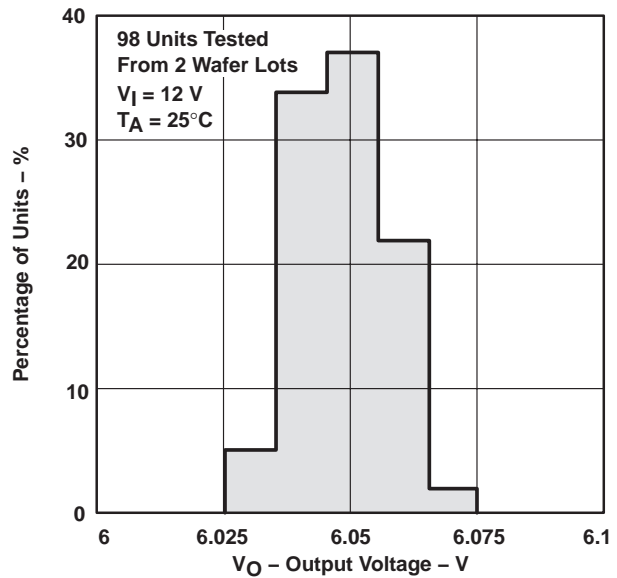
**TYPICAL CHARACTERISTICS†**

**DISTRIBUTION OF OUTPUT VOLTAGE**



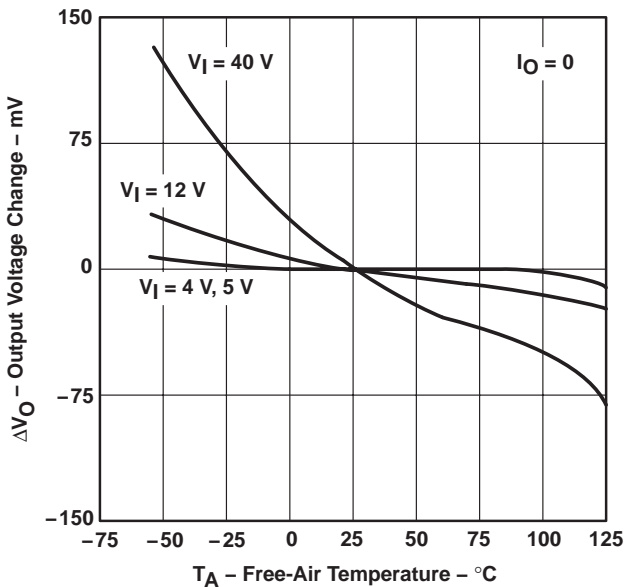
**Figure 1**

**DISTRIBUTION OF OUTPUT VOLTAGE**



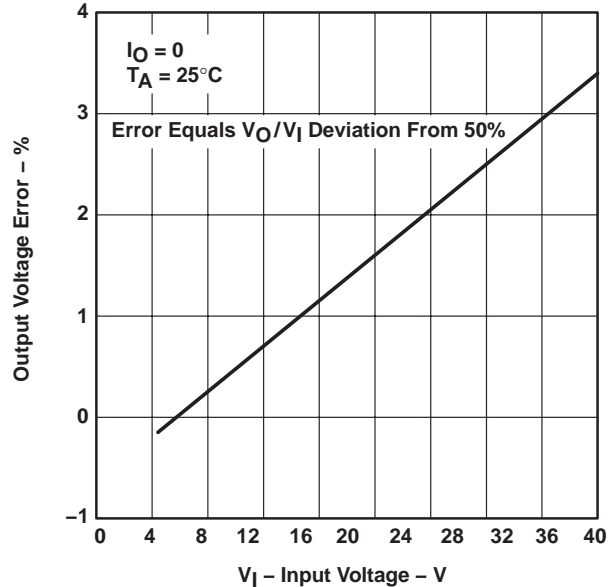
**Figure 2**

**OUTPUT VOLTAGE CHANGE vs FREE-AIR TEMPERATURE**



**Figure 3**

**OUTPUT VOLTAGE ERROR vs INPUT VOLTAGE**



**Figure 4**

† Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.

**TYPICAL CHARACTERISTICS†**

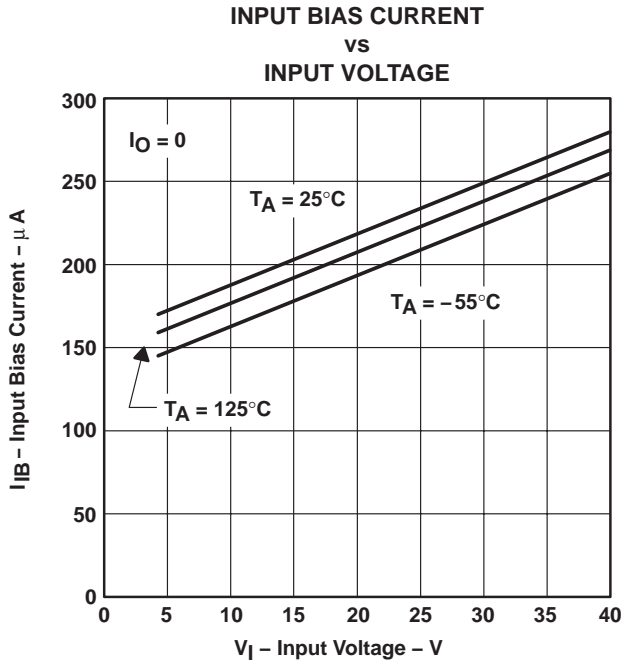


Figure 5

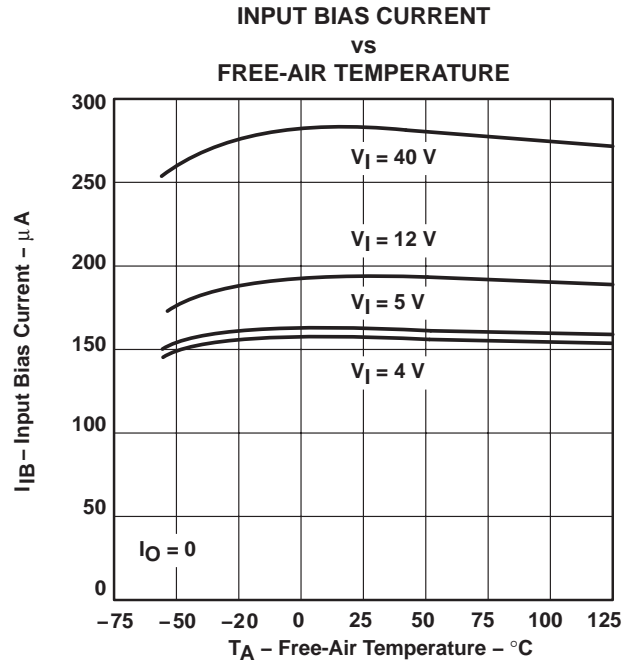


Figure 6

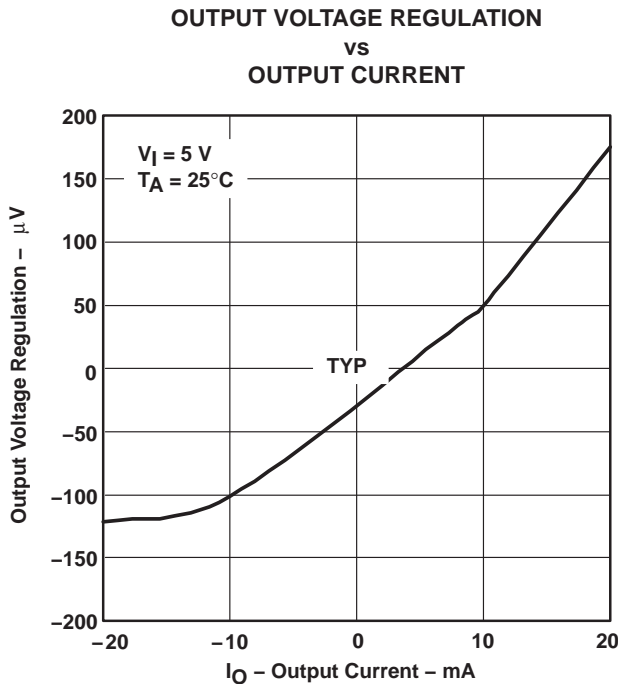


Figure 7

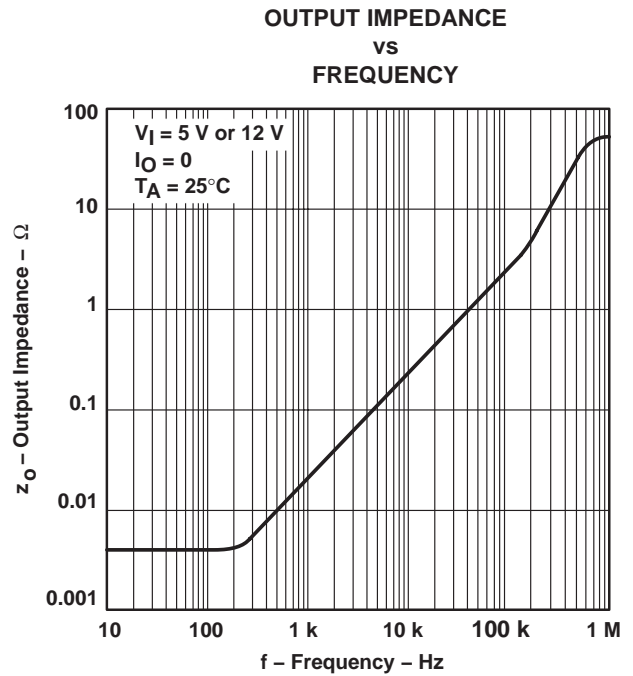


Figure 8

† Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.

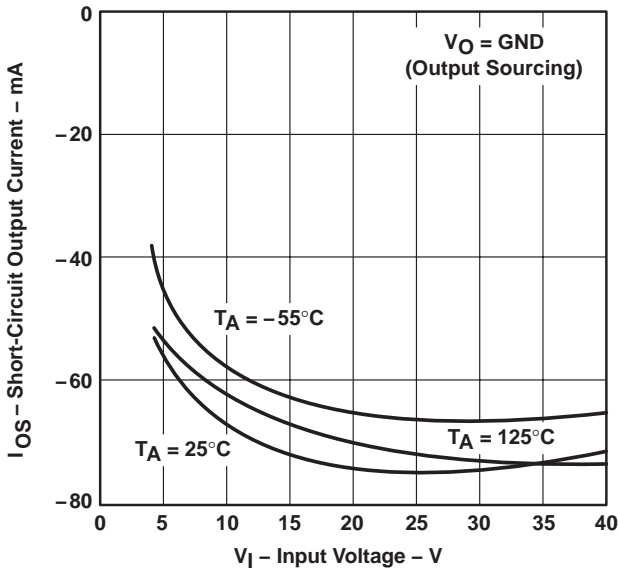


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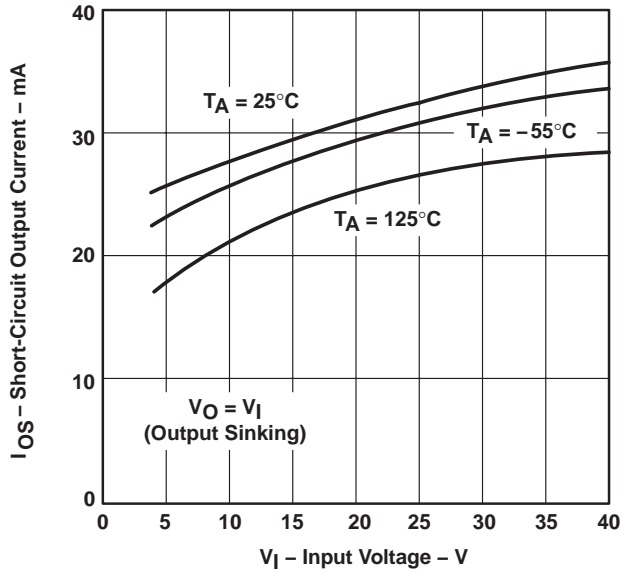
**TYPICAL CHARACTERISTICS†**

**SHORT-CIRCUIT OUTPUT CURRENT  
vs  
INPUT VOLTAGE**



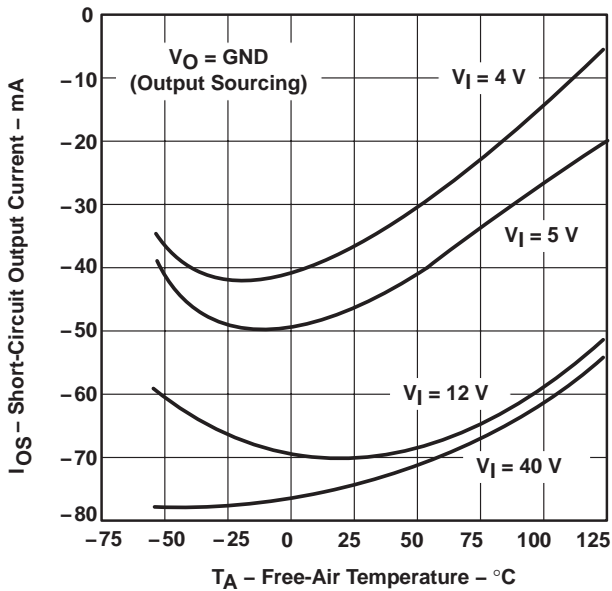
**Figure 9**

**SHORT-CIRCUIT OUTPUT CURRENT  
vs  
INPUT VOLTAGE**



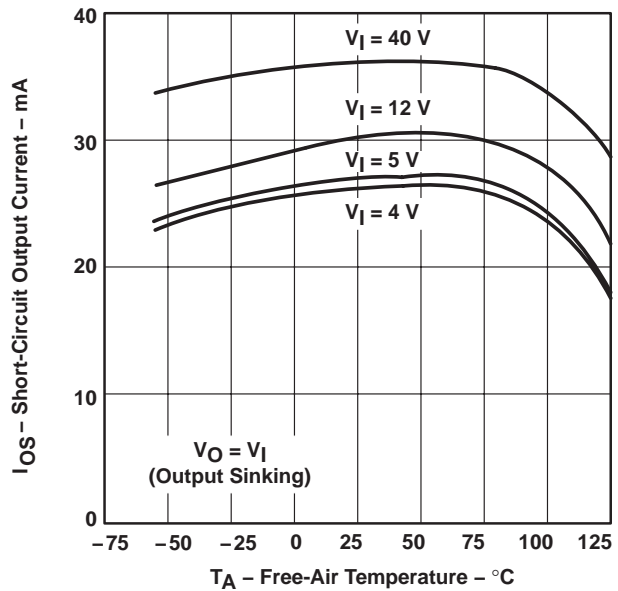
**Figure 10**

**SHORT-CIRCUIT OUTPUT CURRENT  
vs  
FREE-AIR TEMPERATURE**



**Figure 11**

**SHORT-CIRCUIT OUTPUT CURRENT  
vs  
FREE-AIR TEMPERATURE**



**Figure 12**

† Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.

**TYPICAL CHARACTERISTICS**

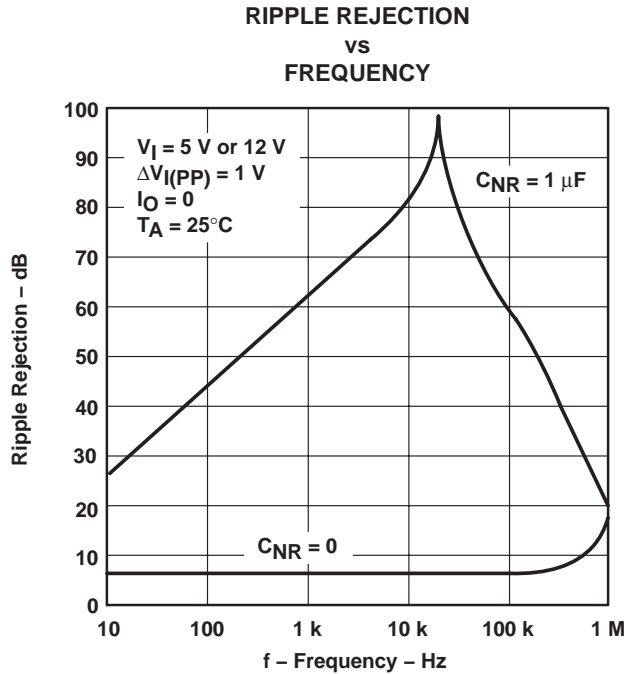


Figure 13

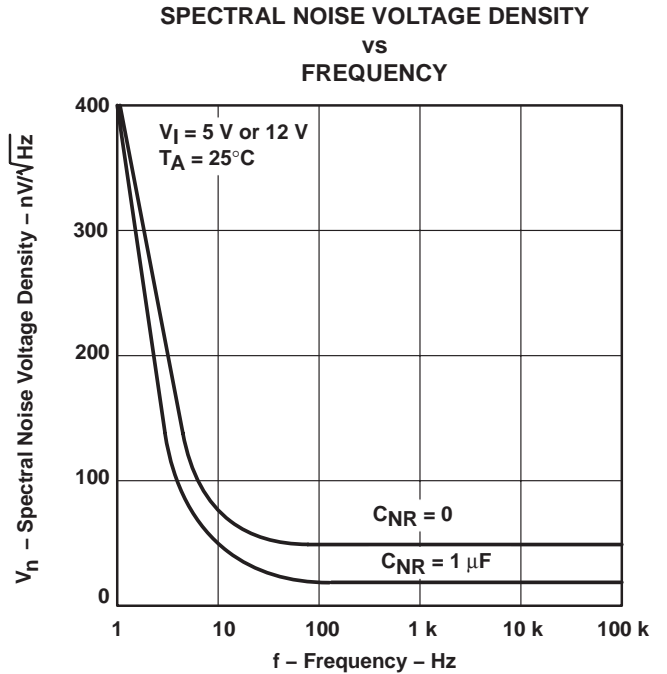


Figure 14

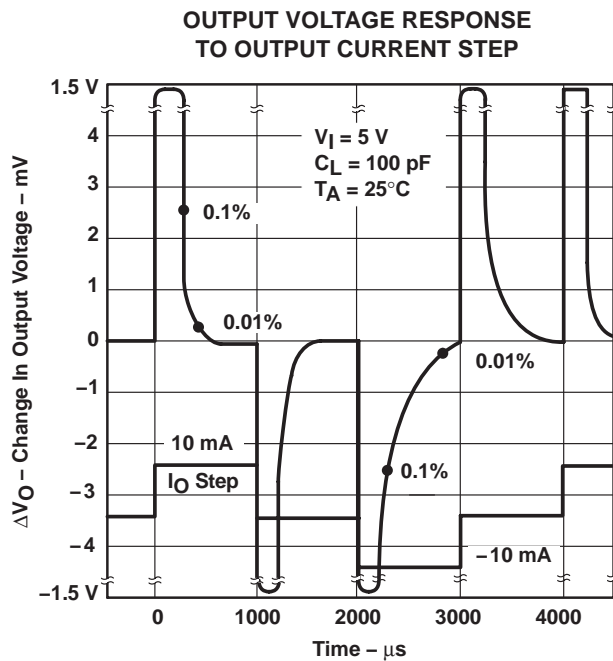


Figure 15

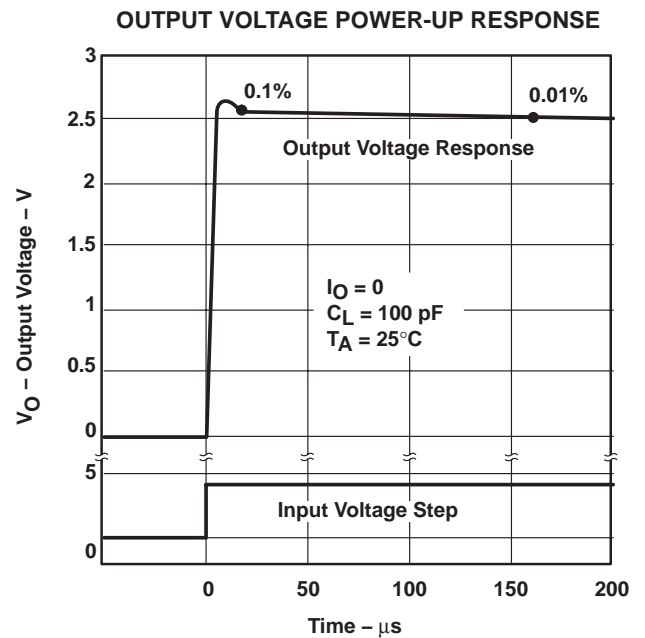
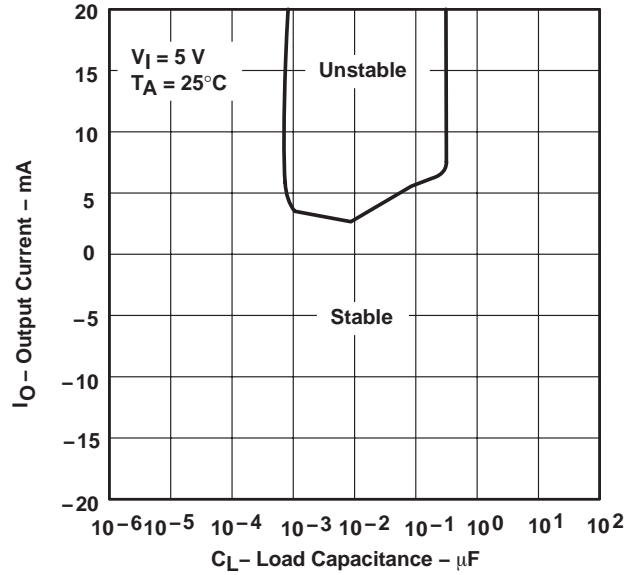


Figure 16

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**TYPICAL CHARACTERISTICS**

STABILITY RANGE  
 OUTPUT CURRENT  
 vs  
 LOAD CAPACITANCE



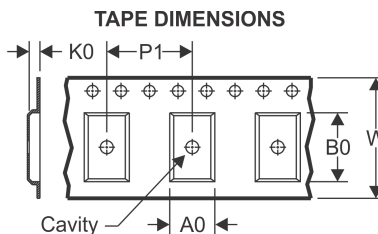
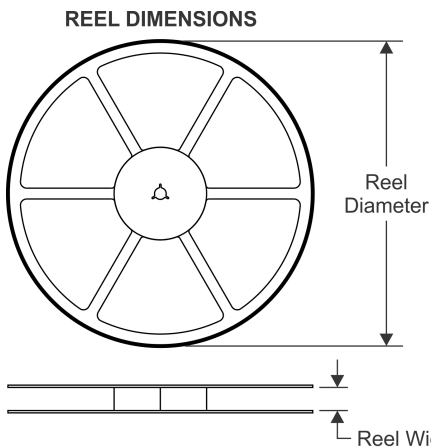
**Figure 17**

**MACROMODEL INFORMATION**

```
* TLE2426 OPERATIONAL AMPLIFIER "MACROMODEL" SUBCIRCUIT
* CREATED USING PARTS RELEASE 4.03 ON 08/21/90 AT 13:51
* REV (N/A) SUPPLY VOLTAGE: 5 V
* CONNECTIONS:
      FILTER
      |
      | INPUT
      | COMMON
      | OUTPUT
*
*
*
.SUBCKT TLE2426      1      3      4      5
```

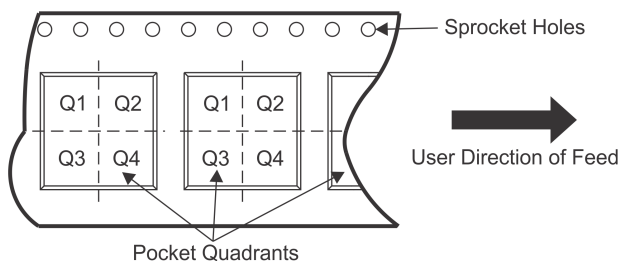
```
C1      11 12 21.66E-12
C2      6  7 30.00E-12
C3      87 0 10.64E-9
CPSR    85 86 15.9E-9
DCM+    81 82 DX
DCM-    83 81 DX
DC      5 53 DX
DE      54 5  DX
DLP     90 91 DX
DLN     92 90 DX
DP      4 3  DX
ECMR    84 99 (2,99) 1
EGND    99 0 POLY(2) (3,0) (4,0) 0 .5 .5
EPSR    85 0 POLY(1) (3,4) -16.22E-6 3.24E-6
ENSE    89 2 POLY(1) (88,0) 120E-6 1
FB      7 99 POLY(6) VB VC VE VLP VLN VPSR 0 74.8E6 -10E6 10E6 10E6 -10E6 74E6
GA      6 0 11 12 320.4E-6
GCM     0 6 10 99 1.013E-9
GPSR    85 86 (85,86) 100E-6
GRC1    4 11 (4,11) 3.204E-4
GRC2    4 12 (4,12) 3.204E-4
GRE1    13 10 (13,10) 1.038E-3
GRE2    14 10 (14,10) 1.038E-3
HLIM    90 0 VLIM 1K
HCMR    80 1 POLY(2) VCM+ VCM- 0 1E2 1E2
IRP     3 4 146E-6
IEE     3 10 DC 24.05E-6
IIO     2 0 .2E-9
I1      88 0 1E-21
Q1      11 89 13 QX
Q2      12 80 14 QX
R2      6 9 100.0E3
RCM     84 81 1K
REE     10 99 8.316E6
RN1     87 0 2.55E8
RN2     87 88 11.67E3
RO1     8 5 63
RO2     7 99 62
VCM+    82 99 1.0
VCM-    83 99 -2.3
VB      9 0 DC 0
VC      3 53 DC 1.400
VE      54 4 DC 1.400
VLIM    7 8 DC 0
VLP     91 0 DC 30
VLN     0 92 DC 30
VPSR    0 86 DC 0
RFB     5 2 1K
RIN1    3 1 220K
RIN2    1 4 220K
.MODEL DX D(IS=800.OE-18)
.MODEL QX PNP(IS=800.OE-18 BF=480)
.ENDS
```

**TAPE AND REEL INFORMATION**



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

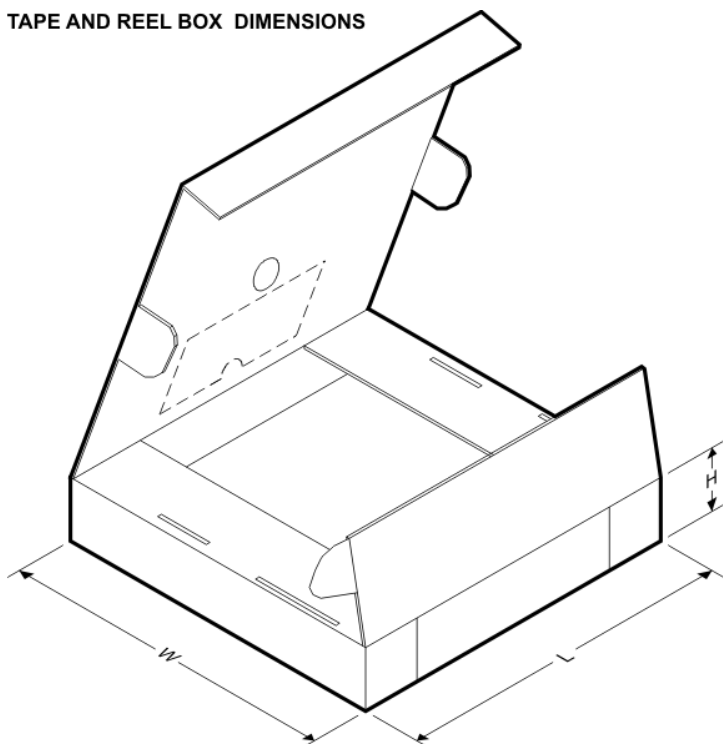
**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLE2426MDREP	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



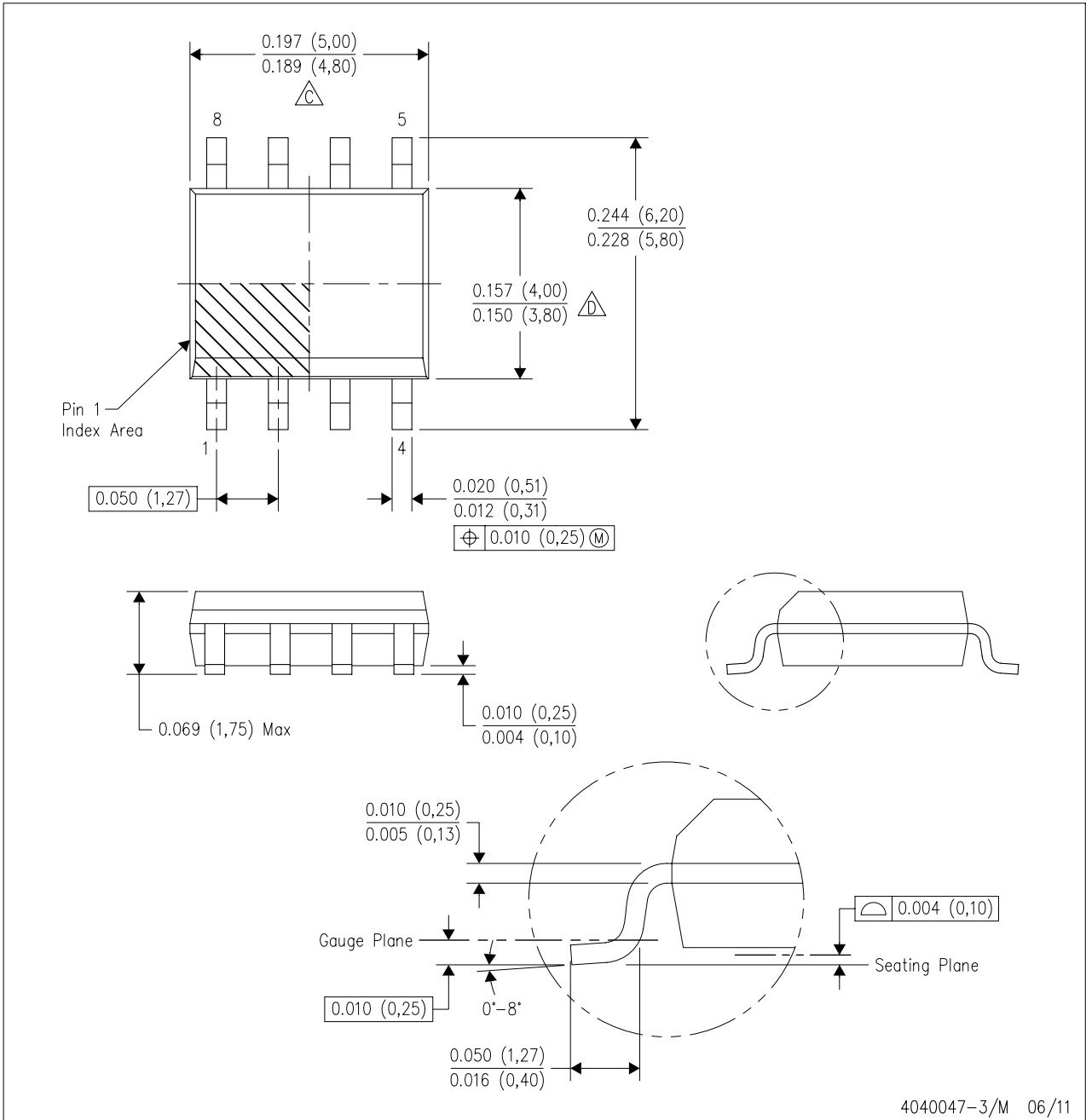
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLE2426MDREP	SOIC	D	8	2500	367.0	367.0	38.0

**MECHANICAL DATA**

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



4040047-3/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - $\triangle D$  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AA.

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